



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Do Not

Application No.: 09/464,322

Filing Date: December 15, 1999

Applicant: Heung-Kyu KWON et al.

Group Art Unit: 2815

Examiner: Chris C. CHU

Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF  
FABRICATING THE SAME

Attorney Docket: 25611-000085/US

Enter

C. C.

7/18/07

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314  
Mail Stop: Amendment

July 9, 2007

AMENDMENT

Sir:

In response to the Office Action mailed May 2, 2007, the following remarks are respectfully submitted in connection with the above-identified application.

**Listing of the Claims** begin on page 3 of this Amendment.

**Remarks** begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
<b>Total</b>	18	-	20	=	0
<b>Independent</b>	3	-	3	=	0